Datasheet revision 1.1

www.chipquik.com

Electronics Grade Silicone Adhesive Sealant (Clear) 10.2oz Cartridge

Product Highlights

Safe for use with Electronics
Seals, Bonds, Encapsulates
Resistant to Various Chemicals and Oils
Non-Corrosive, Non-Conductive
Flexible, Durable, Non-Degrading
Withstands Moisture, Vibration, Abrasion

Common Uses

Protecting, Sealing and Insulating Corrosion Sensitive Electronic Components and Electrical Materials.
OEM Commercial and Industrial Manufacturing for Flexible Permanent Bonding and Sealing.

Instructions

Surfaces should be clean and dry. For detached nozzle cartridge, cut the tip off of the cartridge just above the nozzle threads. Thread nozzle onto cartridge and cut the tip off of the nozzle to the required bead size. Dispense by pushing the silicone in the direction of the nozzle with a cartridge dispensing gun. If tooling is required, do so within the first 10 minutes after dispensing. Apply the silicone to surfaces and remove the excess silicone after tooling with a dry clean cloth. Allow the silicone to cure completely. At room temperature, 25°C (77°F), and 50% relative humidity, the silicone will skin in 10 minutes and fully cure in 24 hours (1/8" bead). The silicone will reach its maximum adhesion in 7 days. Higher humidity accelerates curing.

Specifications

Meets and Exceeds:	ASTM C920, UL Recognized
VOC:	VOC Compliant (<3%), Low Odor
Operating Temperature Range:	-57°C to +204°C (-70°F to +400°F)
Curing Time:	10 min (skin), 24 hours (full cure), 7 days (max adhesion)
Color:	Clear
Size:	10.2oz Cartridge
Shore A Hardness:	30
Tensile Strength:	250psi
Tear Strength:	30psi
Elongation:	400%
Dielectric Strength:	460 V/mil (18 kV/mm)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F).

Shelf Life

>36 months

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.